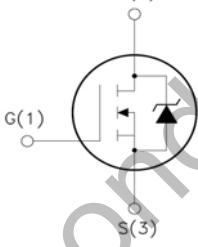


 WGD120N03	 TO-252
Features: <ul style="list-style-type: none"> <input type="checkbox"/> Low Intrinsic Capacitances. <input type="checkbox"/> Excellent Switching Characteristics. <input type="checkbox"/> Extended Safe Operating Area. <input type="checkbox"/> Unrivalled Gate Charge :$Q_g = 70\text{nC}$ (Typ.). <input type="checkbox"/> $\text{BV}_{\text{DSS}}=30\text{V}, I_{\text{D}}=120\text{A}$ <input type="checkbox"/> $R_{\text{DS(on)}} : 4.2\text{m}\Omega$ (Max) @ $V_{\text{G}}=10\text{V}$ <input type="checkbox"/> 100% Avalanche Tested 	  1.Gate (G) 2.Drain (D) 3.Source (S)

Absolute Maximum Ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	30	V
I_{D}	Drain Current	$T_j=25^\circ\text{C}$	120
		$T_j=100^\circ\text{C}$	70
V_{GSS}	Gate Threshold Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy (note5)	350	mJ
I_{DM}	Pulsed Drain Current	400	A
P_{D}	Power Dissipation ($T_j=25^\circ\text{C}$)	110	W
T_j	Junction Temperature(Max)	175	$^\circ\text{C}$
T_{stg}	Storage Temperature	-55~+175	
T_L	Maximum lead temperature for soldering purpose, 1/8" from case for 5 seconds	300	

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta_{\text{JC}}}$	Thermal Resistance,Junction to Case	-	1.36	$^\circ\text{C}/\text{W}$

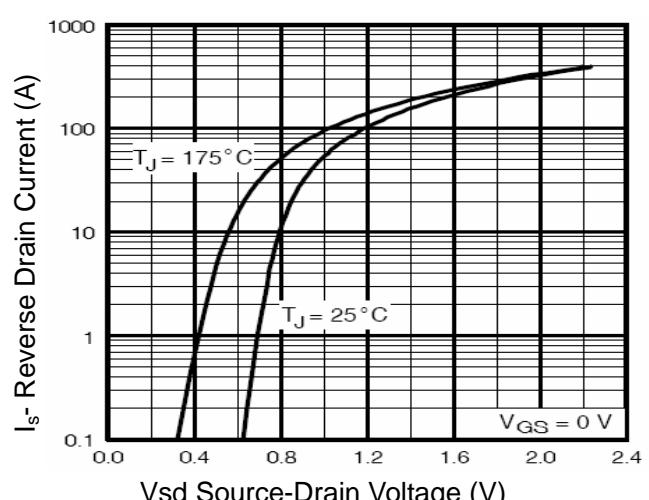
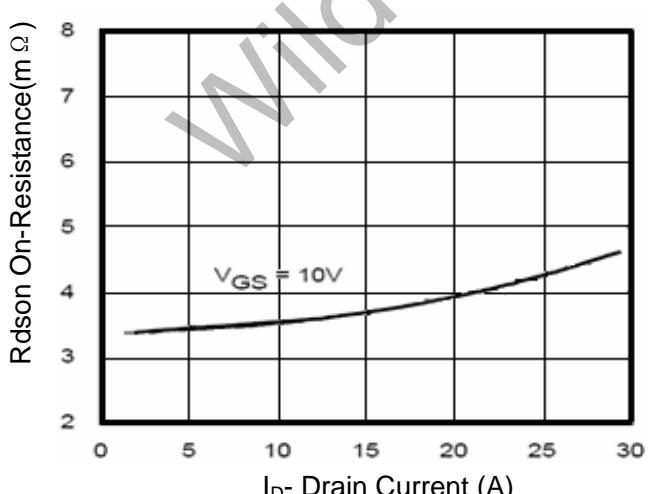
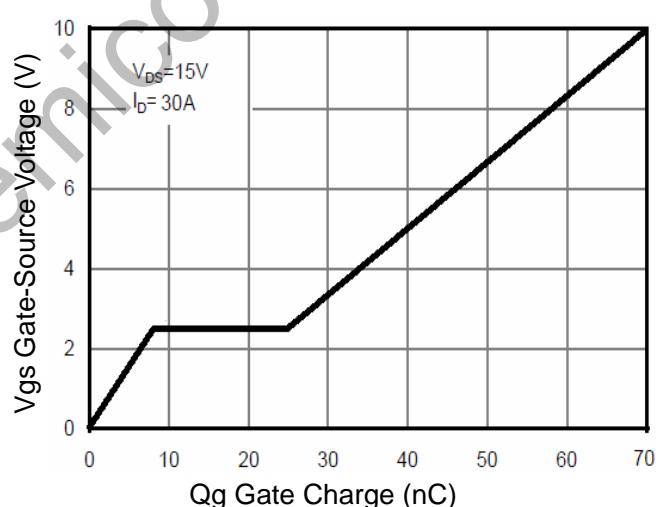
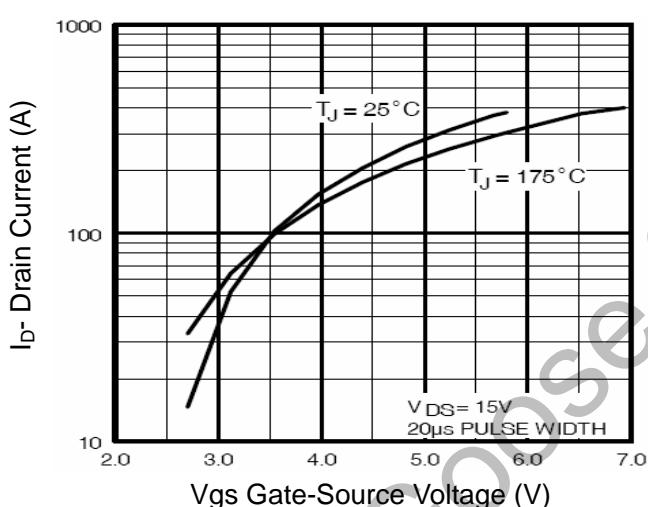
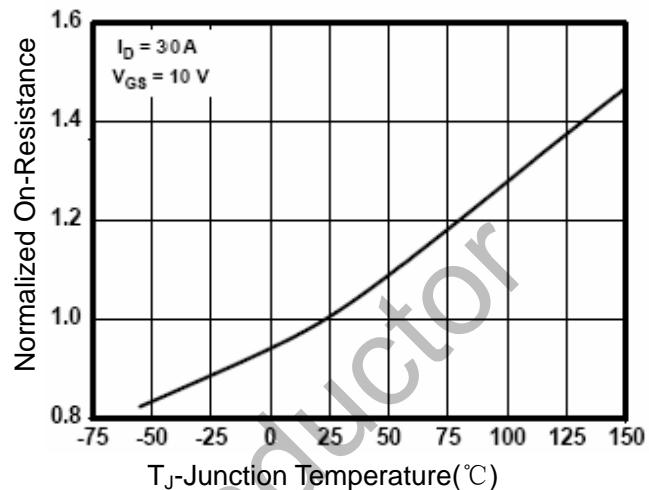
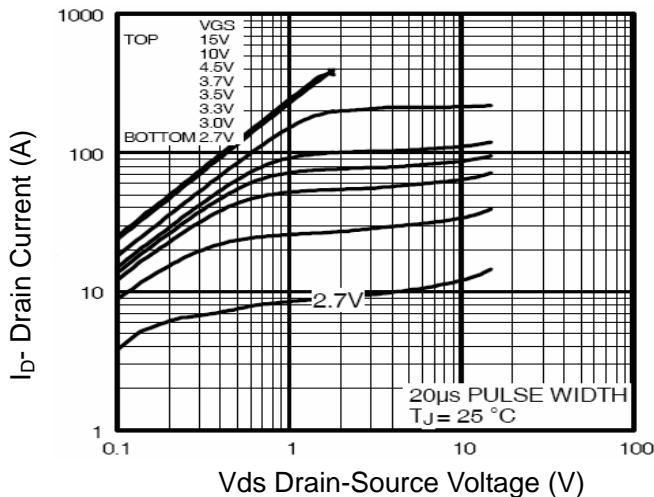
Electrical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{\text{DS}}=30\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
On Characteristics <small>(Note 3)</small>						
Gate Threshold Voltage	$V_{\text{GS(th)}}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1	1.6	3	V
Drain-Source On-State Resistance	$R_{\text{DS(ON)}}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=20\text{A}$	-	3.3	4.2	$\text{m}\Omega$
Forward Transconductance	g_{FS}	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=20\text{A}$	50	-	-	S
Dynamic Characteristics <small>(Note 4)</small>						
Input Capacitance	C_{iss}	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$		3400		PF
Output Capacitance	C_{oss}			356		PF
Reverse Transfer Capacitance	C_{rss}			308		PF
Switching Characteristics <small>(Note 4)</small>						
Turn-on Delay Time	$t_{\text{d(on)}}$	$V_{\text{DD}}=15\text{V}, I_{\text{D}}=60\text{A}$ $V_{\text{GS}}=4.5\text{V}, R_{\text{GEN}}=1.8\Omega$	-	11	-	nS
Turn-on Rise Time	t_r		-	160	-	nS
Turn-Off Delay Time	$t_{\text{d(off)}}$		-	25	-	nS
Turn-Off Fall Time	t_f		-	60	-	nS
Total Gate Charge	Q_g	$V_{\text{DS}}=15\text{V}, I_{\text{D}}=30\text{A}, V_{\text{GS}}=10\text{V}$		70		nC
Gate-Source Charge	Q_{gs}			8.8		nC
Gate-Drain Charge	Q_{gd}			16.3		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage <small>(Note 3)</small>	V_{SD}	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=20\text{A}$	-	-	1.2	V
Diode Forward Current <small>(Note 2)</small>	I_{S}	-	-	-	120	A
Reverse Recovery Time	t_{rr}	$T_J = 25^\circ\text{C}, IF = 60\text{A}$ $di/dt = 100\text{A}/\mu\text{s}$ <small>(Note 3)</small>	-	56	-	nS
Reverse Recovery Charge	Q_{rr}		-	110	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, $t \leq 10$ sec.
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production
5. EAS condition: $T_j=25^\circ\text{C}, V_{\text{DD}}=15\text{V}, V_{\text{G}}=10\text{V}, L=0.5\text{mH}, R_g=25\Omega$

Typical Electrical and Thermal Characteristics (Curves)



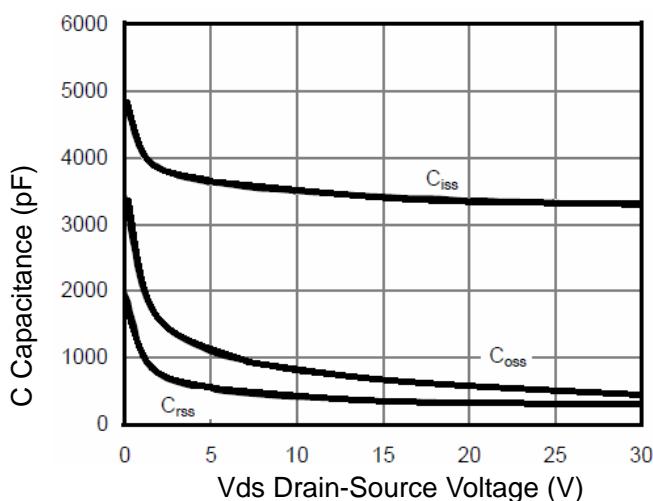


Figure 7 Capacitance vs Vds

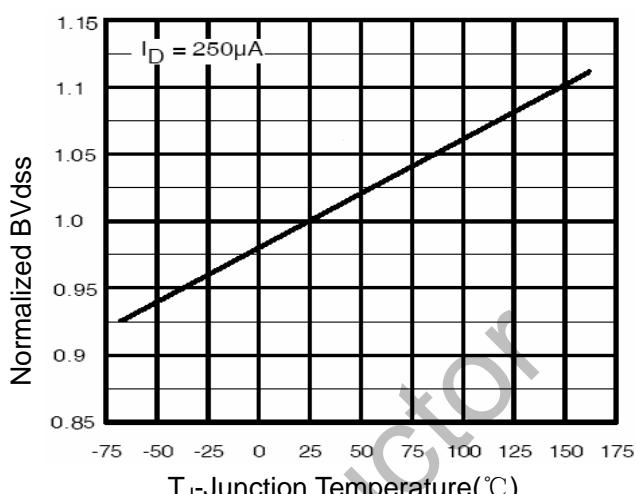
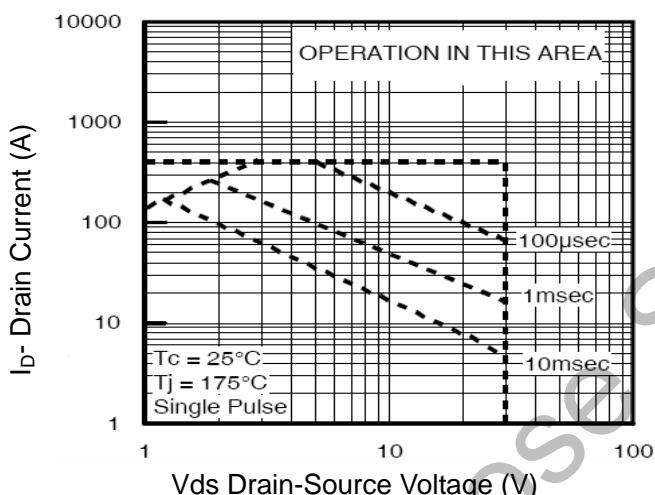
Figure 9 BV_{dss} vs Junction Temperature

Figure 8 Safe Operation Area

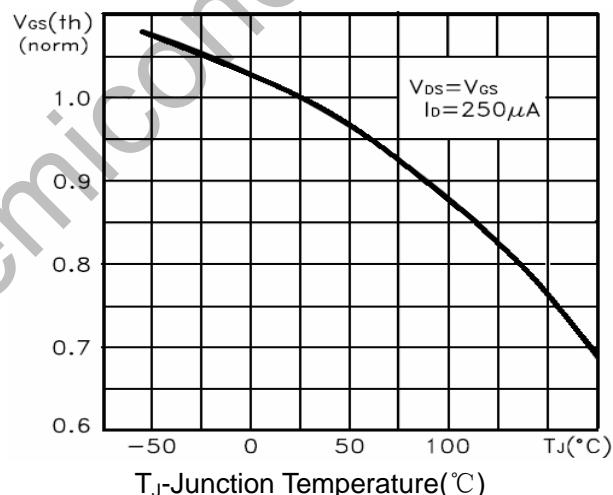
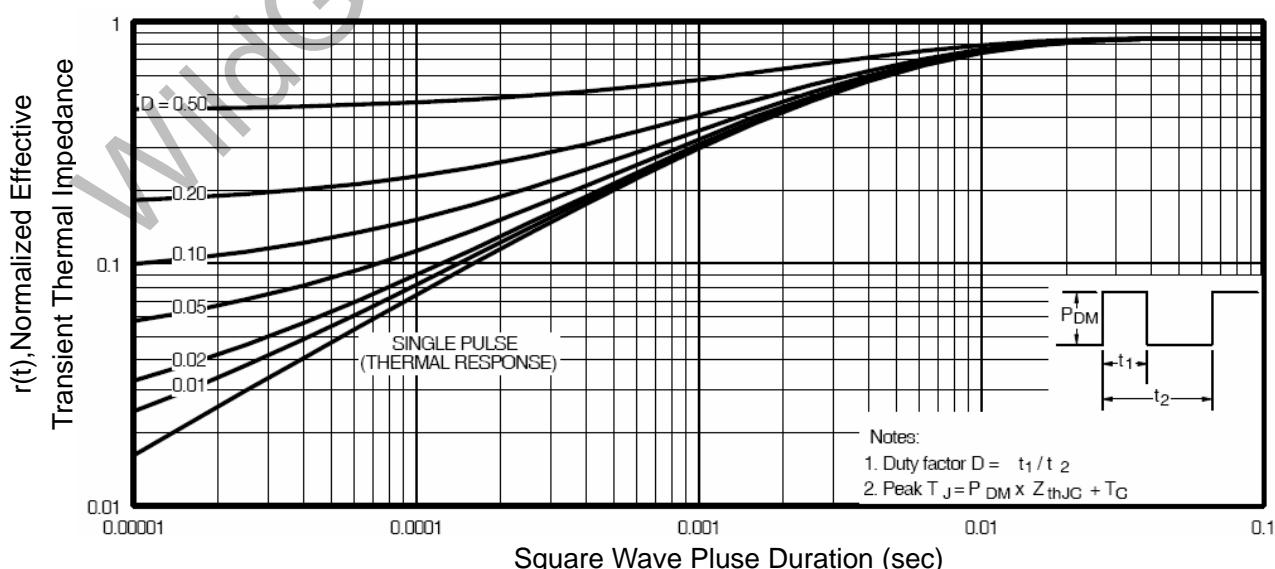
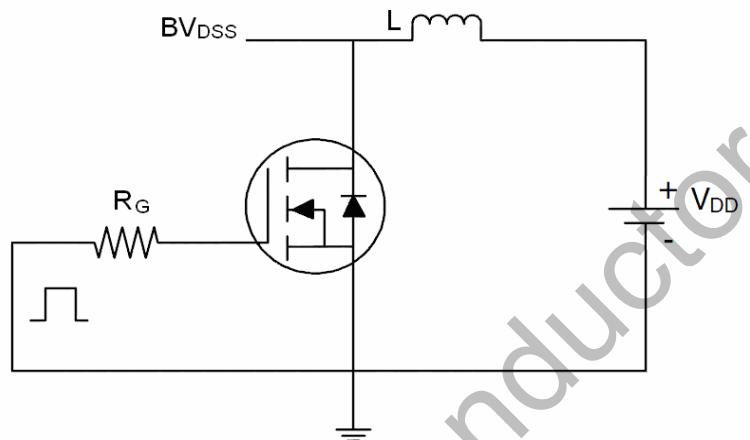
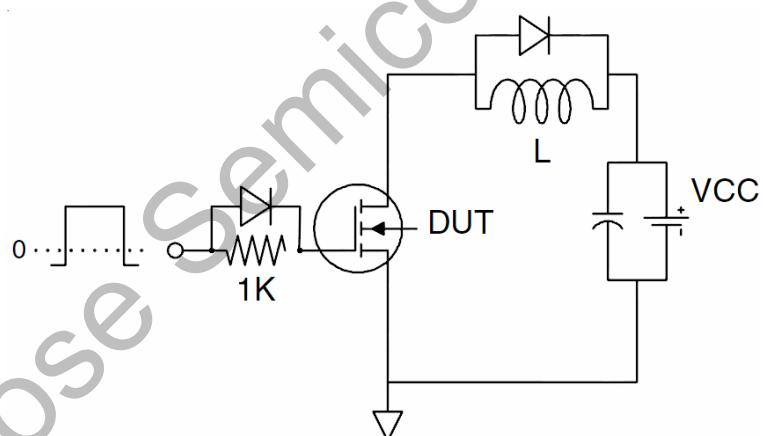
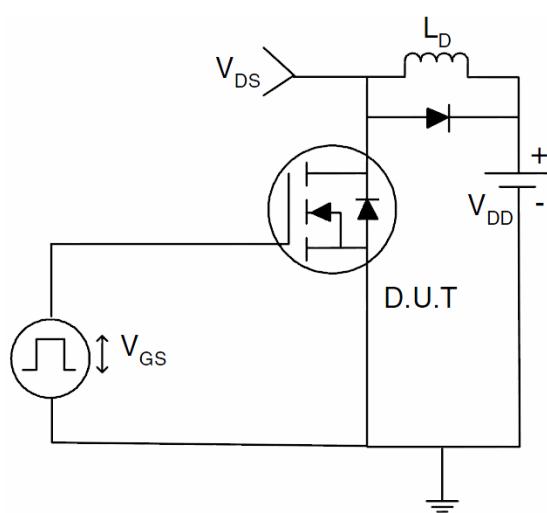
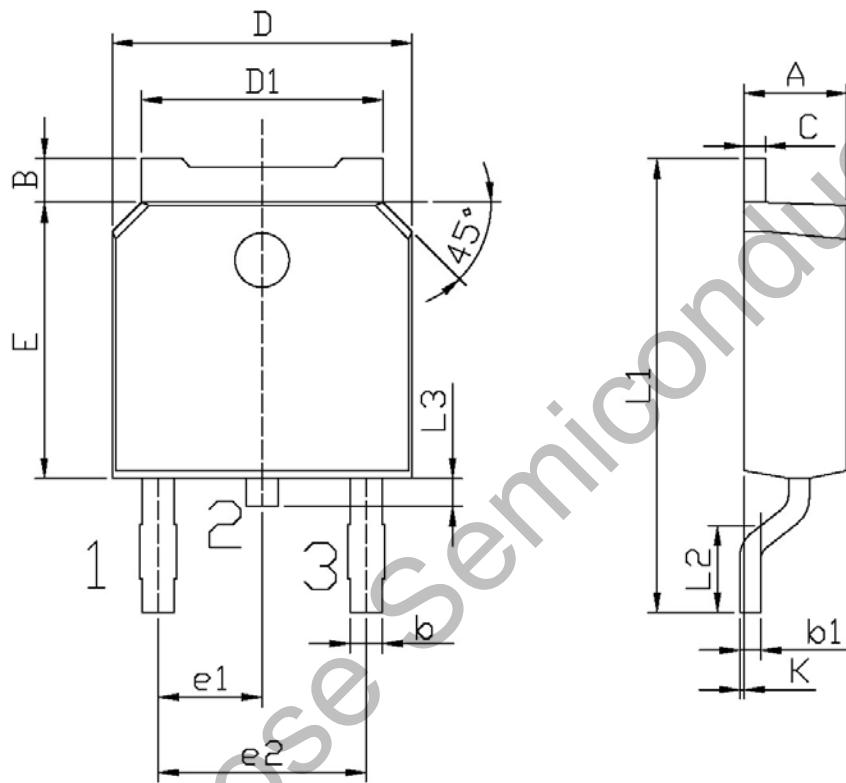
Figure 10 $V_{GS(th)}$ vs Junction Temperature

Figure 11 Normalized Maximum Transient Thermal Impedance

Test circuit**1) E_{AS} test Circuit****2) Gate charge test Circuit****3) Switch Time Test Circuit**

Package Dimension**TO-252**

Unit: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	2.20	2.40	E	5.95	6.25
B	0.95	1.25	e1	2.24	2.34
b	0.70	0.90	e2	4.43	4.73
b1	0.45	0.55	L1	9.85	10.35
C	0.45	0.55	L2	1.25	1.75
D	6.45	6.75	L3	0.60	0.90
D1	5.20	5.40	K	0.00	0.10